

DESCRIPTION

The SPP3421 is the P-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology.

This high density process is especially tailored to minimize on-state resistance.

These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits, and low in-line power loss are needed in a very small outline surface mount package.

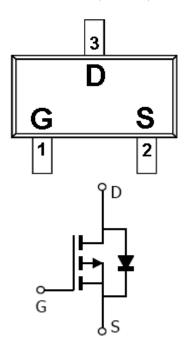
APPLICATIONS

- Power Management in Note book
- Portable Equipment
- Battery Powered System
- DC/DC Converter
- Load Switch
- DSC
- LCD Display inverter

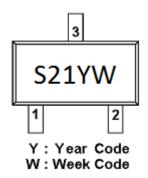
FEATURES

- -60V/-5A, RDS(ON)= $150m\Omega$ @VGS=-10V
- -60V/-2.5A, RDS(ON)= $185m\Omega$ @VGS=-4.5V
- ◆ Super high density cell design for extremely low RDS (ON)
- Exceptional on-resistance and maximum DC current capability
- ◆ SOT-23 package design

PIN CONFIGURATION(SOT-23)



PART MARKING



PIN DESCRIPTION						
Pin	Symbol	Description				
1	G	Gate				
2	S	Source				
3	D	Drain				

ORDERING INFORMATION

Part Number	Package	Part Marking
SPP3421S23RGB	SOT-23	S21YW

Week Code: $A \sim Z(1 \sim 26)$; $a \sim z(27 \sim 52)$

※ SPP3421S23RGB: Tape Reel; Pb − Free; Halogen − Free

ABSOULTE MAXIMUM RATINGS

(Ta=25°C Unless otherwise noted)

Parameter	Symbol	Typical	Unit	
Drain-Source Voltage		Vdss	-60	V
Gate –Source Voltage		VGSS	±20	V
Continuous Drain Current(Tr-150°C)	TA=25°C	In	-5	Α.
Continuous Drain Current(TJ=150°C)	TA=70°C	- Id	-3.5	A
Pulsed Drain Current	Ірм	-12	A	
Continuous Source Current(Diode Conduct	Is	-1.25	A	
D D' : '	Ta=25°C	D-	1.25	W
Power Dissipation	Ta=70°C	PD	0.8	W
Operating Junction Temperature	Тл	150	$^{\circ}\! \mathbb{C}$	
Storage Temperature Range		Tstg	-55/150	$^{\circ}\!\mathbb{C}$
Thermal Resistance-Junction to Ambient		R _θ JA	100	°C/W

ELECTRICAL CHARACTERISTICS

(Ta=25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Тур	Max.	Unit	
Static	l		L	ı		•	
Drain-Source Breakdown Voltage	V(BR)DSS	VGS=0V,ID=-250uA	-60			V	
Gate Threshold Voltage	VGS(th)	VDS=VGS,ID=-250uA	-1		-3		
Gate Leakage Current	Igss	V _{DS} =0V,V _{GS} =±20V			±100	nA	
		V _{DS} =-48V,V _{GS} =0V			-1	uA	
Zero Gate Voltage Drain Current	Idss	V_{DS} =-48 V , V_{GS} =0 V			-10		
On-State Drain Current	ID(on)	$V_{DS} \leq -5V, V_{GS} = -10V$			-5	A	
	1D(011)	$V_{DS} \leq -5V, V_{GS} = -4.5V$			-2.5		
Drain-Source On-Resistance	RDS(on)	V _{GS} =-10V,I _D =-5A		150	160	mΩ	
	. , ,	V _{GS} =-4.5V,I _D =-2.5A		185	200	~	
Forward Transconductance	gfs	VDS=-10V,ID=-1.7A		2.4		S	
Diode Forward Voltage	Vsd	Is=-1.25A,VGS=0V		-0.8	-1.2	V	
Dynamic							
Total Gate Charge	Qg			16			
Gate-Source Charge	Qgs	V _{DS} =-30V,V _{GS} =-10V I _D =-2A		8		nC	
Gate-Drain Charge	Qgd	-ID2A		3.0			
Input Capacitance	Ciss				1200	pF	
Output Capacitance	Coss	V _{DS} =-30V,V _{GS} =0V -f=1MHz		115			
Reverse Transfer Capacitance	Crss			7		-	
	td(on)			9		ns	
Turn-On Time	tr	V _{DD} =-10V,R _L =15Ω		109			
T. OMT.	td(off)	-ID=-1.0A,VGEN=-3V RG=2.5Ω		25			
Turn-Off Time	tf			11			

TYPICAL CHARACTERISTICS

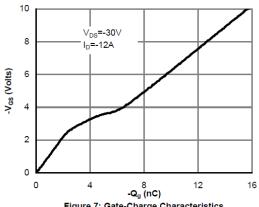


Figure 7: Gate-Charge Characteristics

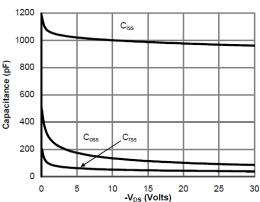


Figure 8: Capacitance Characteristics

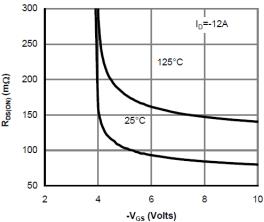


Figure 5: On-Resistance vs. Gate-Source Voltage

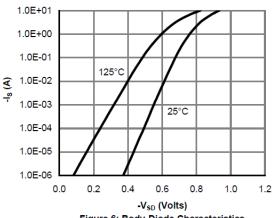


Figure 6: Body-Diode Characteristics

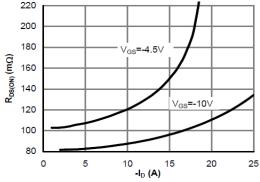


Figure 3: On-Resistance vs. Drain Current and **Gate Voltage**

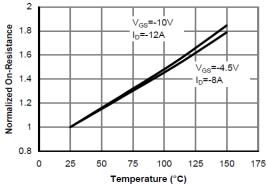
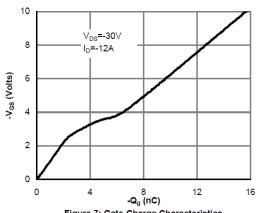
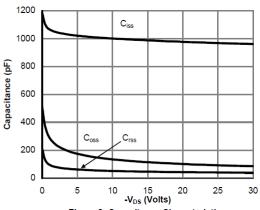


Figure 4: On-Resistance vs. Junction Temperature

TYPICAL CHARACTERISTICS





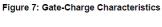


Figure 8: Capacitance Characteristics

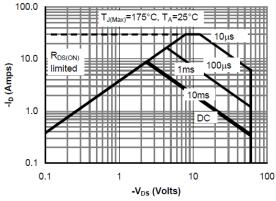


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

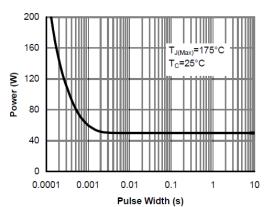


Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

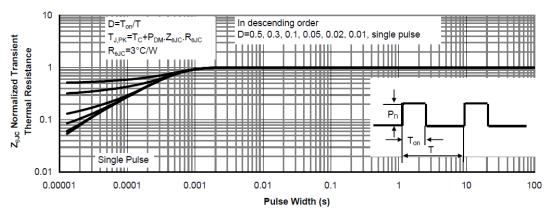
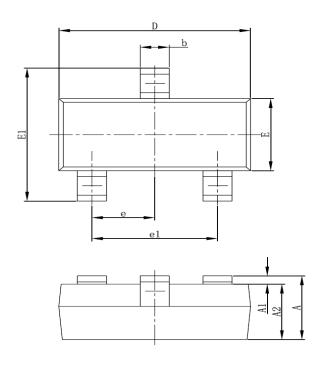
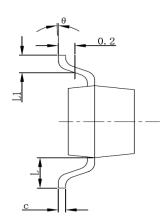


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

SOT-23 PACKAGE OUTLINE





Symbol	Dimensions In Millimeters		Dimensions In Inches		
Syllibol	Min	Max	Min	Max	
Α	0.900	1.100	0.035	0.043	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.000	0.035	0.039	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
Е	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950TYP		0.037TYP		
e1	1.800	2.000	0.071	0.079	
L	0.550REF		0.02	2REF	
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

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